

# PSMN6R1-40HL

N-channel 40 V, 7.2 mOhm, logic level MOSFET in LFPAK56D using TrenchMOS technology

30 September 2022

**Product data sheet** 

# 1. General description

Dual logic level N-channel MOSFET in an LFPAK56D (Dual Power-SO8) package using TrenchMOS technology.

### 2. Features and benefits

- Dual MOSFET
- · Repetitive avalanche rated
- · High reliability LFPAK56D package
- · Copper-clip, solder die attach
- Qualified to 175 °C

# 3. Applications

- · Brushless DC motor control
- DC-to-DC converters
- · High-performance synchronous rectification
- · High performance and high efficiency server power supply

### 4. Quick reference data

#### Table 1. Quick reference data

Symbol	Parameter	Conditions		Min	Тур	Max	Unit
$V_{DS}$	drain-source voltage	25 °C ≤ T <sub>j</sub> ≤ 175 °C		-	-	40	V
I <sub>D</sub>	drain current	V <sub>GS</sub> = 5 V; T <sub>mb</sub> = 25 °C; <u>Fig. 2</u>	[1]	-	-	40	Α
P <sub>tot</sub>	total power dissipation	T <sub>mb</sub> = 25 °C; <u>Fig. 1</u>		-	-	64	W
Tj	junction temperature			-55	-	175	°C
Static chara	cteristics FET1 and FET2				'	'	'
R <sub>DSon</sub> drain-source on-state resistance		$V_{GS} = 5 \text{ V}; I_D = 10 \text{ A}; T_j = 25 \text{ °C}; Fig. 11$		-	6	7.2	mΩ
	$V_{GS}$ = 5 V; $I_D$ = 10 A; $T_j$ = 175 °C; Fig. 11		-	12.1	14.5	mΩ	
Dynamic ch	aracteristics FET1 and FE	T2					
$Q_{GD}$	gate-drain charge	I <sub>D</sub> = 10 A; V <sub>DS</sub> = 32 V; V <sub>GS</sub> = 5 V;		-	6.8	-	nC
Q <sub>G(tot)</sub>	total gate charge	T <sub>j</sub> = 25 °C; <u>Fig. 13; Fig. 14</u>		-	22.2	-	nC
Avalanche r	uggedness FET1 and FET	2					"
E <sub>DS(AL)S</sub>	non-repetitive drain- source avalanche energy	$I_D = 40 \text{ A}; V_{sup} \le 40 \text{ V}; V_{GS} = 10 \text{ V}; $ $T_{j(init)} = 25 \text{ °C}; Fig. 4$	[2] [3]	-	-	125	mJ



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Symbol	Parameter	Conditions		Min	Тур	Max	Unit
Source-drain d	Source-drain diode FET1 and FET2						
Q <sub>r</sub>		$I_S$ = 10 A; $dI_S/dt$ = -100 A/ $\mu$ s; $V_{GS}$ = 0 V; $V_{DS}$ = 20 V; $T_j$ = 25 °C		-	18	-	nC

- [1] Continuous current is limited by package.
- [2] Refer to application note AN10273 for further information
- [3] Single-pulse avalanche rating limited by maximum junction temperature of 175 °C

# 5. Pinning information

**Table 2. Pinning information** 

Pin	Symbol	Description	Simplified outline	Graphic symbol		
1	S1	source1	8 7 6 5			
2	G1	gate1	1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1 1	D1 D1 D2 D2		
3	S2	source2				
4	G2	gate2				
5	D2	drain2				
6	D2	drain2				
7	D1	drain1		S1 G1 S2 G2		
8	D1	drain1	LFPAK56D; Dual LFPAK (SOT1205)	mbk725		

# 6. Ordering information

**Table 3. Ordering information** 

Type number	Package	ackage				
	Name	Description	Version			
PSMN6R1-40HL		plastic, single ended surface mounted package (LFPAK56D); 8 leads	SOT1205			

# 7. Marking

Table 4. Marking codes

Type number	Marking code
PSMN6R1-40HL	6R1L40H

# 8. Limiting values

#### Table 5. Limiting values

In accordance with the Absolute Maximum Rating System (IEC 60134).

Symbol	Parameter	Conditions		Min	Max	Unit
V <sub>DS</sub>	drain-source voltage	25 °C ≤ T <sub>j</sub> ≤ 175 °C		-	40	V
$V_{DGR}$	drain-gate voltage	$R_{GS}$ = 20 k $\Omega$		-	40	V
$V_{GS}$	gate-source voltage	Pulsed; T <sub>j</sub> ≤ 175 °C	[1] [2]	-15	15	V
		DC; T <sub>j</sub> ≤ 175 °C		-10	10	V
P <sub>tot</sub>	total power dissipation	T <sub>mb</sub> = 25 °C; <u>Fig. 1</u>		-	64	W

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Symbol	Parameter	Conditions		Min	Max	Unit
I <sub>D</sub>	drain current	V <sub>GS</sub> = 5 V; T <sub>mb</sub> = 25 °C; <u>Fig. 2</u>	[3]	-	40	Α
		V <sub>GS</sub> = 5 V; T <sub>mb</sub> = 100 °C; <u>Fig. 2</u>	[3]	-	40	А
I <sub>DM</sub>	peak drain current	pulsed; $t_p \le 10 \mu s$ ; $T_{mb} = 25 °C$ ; Fig. 3		-	265	А
T <sub>stg</sub>	storage temperature			-55	175	°C
Tj	junction temperature			-55	175	°C
Source-drain d	iode FET1 and FET2				'	'
I <sub>S</sub>	source current	T <sub>mb</sub> = 25 °C	[3]	-	40	А
I <sub>SM</sub>	peak source current	pulsed; t <sub>p</sub> ≤ 10 µs; T <sub>mb</sub> = 25 °C		-	265	Α
Avalanche ruge	gedness FET1 and FET2			'	'	'
E <sub>DS(AL)S</sub>	non-repetitive drain- source avalanche energy	$I_D = 40 \text{ A; } V_{sup} \le 40 \text{ V; } V_{GS} = 10 \text{ V;} $ $T_{j(init)} = 25 \text{ °C; } Fig. 4$	[4] [5]	-	125	mJ

- [1] Accumulated Pulse duration up to 50 hours delivers zero defect ppm
- [2] Significantly longer life times are achieved by lowering  $T_j$  and or  $V_{GS}$ .
- [3] Continuous current is limited by package.
- [4] Refer to application note AN10273 for further information
- [5] Single-pulse avalanche rating limited by maximum junction temperature of 175 °C

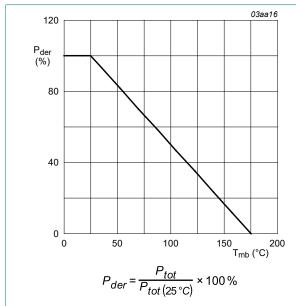
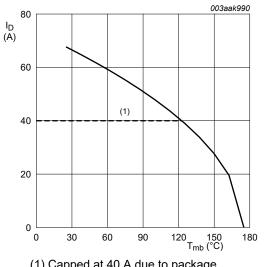


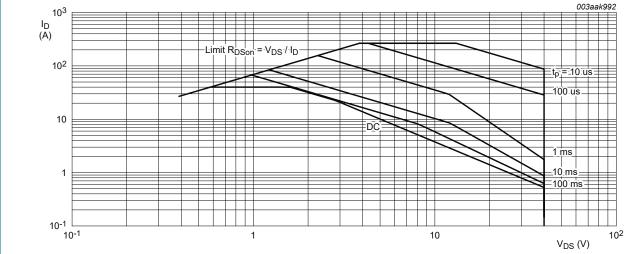
Fig. 1. Normalized total power dissipation as a function of mounting base temperature



(1) Capped at 40 A due to package  $V_{GS} \ge 5 \text{ V}$ 

Fig. 2. Continuous drain current as a function of mounting base temperature

#### N-channel 40 V, 7.2 mOhm, logic level MOSFET in LFPAK56D using TrenchMOS technology



 $T_{mb}$  = 25 °C;  $I_{DM}$  is a single pulse

Fig. 3. Safe operating area; continuous and peak drain currents as a function of drain-source voltage

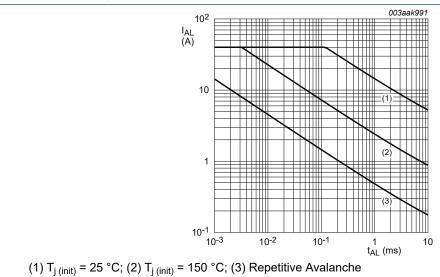


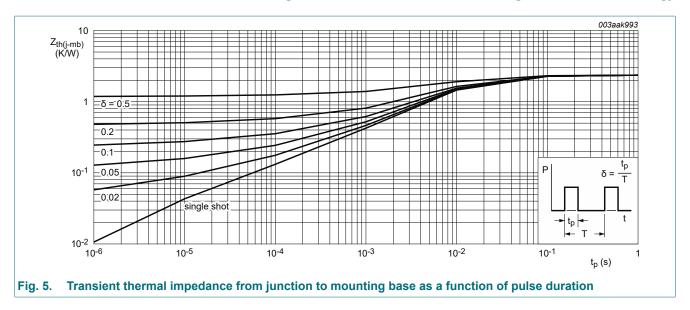
Fig. 4. Avalanche rating; avalanche current as a function of avalanche time

### 9. Thermal characteristics

**Table 6. Thermal characteristics** 

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
R <sub>th(j-mb)</sub>	thermal resistance from junction to mounting base	Fig. 5	-	-	2.36	K/W
$R_{th(j-a)}$	thermal resistance from junction to ambient	Minimum footprint; mounted on a printed circuit board	-	95	-	K/W

### N-channel 40 V, 7.2 mOhm, logic level MOSFET in LFPAK56D using TrenchMOS technology



### 10. Characteristics

**Table 7. Characteristics** 

Symbol	Parameter	Conditions	Min	Тур	Max	Unit
Static chara	acteristics FET1 and FET2					
V <sub>(BR)DSS</sub>	drain-source	$I_D = 250 \mu A; V_{GS} = 0 V; T_j = -55 °C$	36	-	-	V
	breakdown voltage	I <sub>D</sub> = 250 μA; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C	40	-	-	V
V <sub>GS(th)</sub>	gate-source threshold voltage	$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = 25 \text{ °C}; Fig. 9;$ Fig. 10	1.4	1.7	2.1	V
		I <sub>D</sub> = 1 mA; V <sub>DS</sub> =V <sub>GS</sub> ; T <sub>j</sub> = 175 °C; <u>Fig. 9</u> ; <u>Fig. 10</u>	0.5	-	-	V
		$I_D = 1 \text{ mA}; V_{DS} = V_{GS}; T_j = -55 \text{ °C}; Fig. 9;$ Fig. 10	-	-	2.45	V
I <sub>DSS</sub>	drain leakage current	V <sub>DS</sub> = 40 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 175 °C	-	-	500	μA
		V <sub>DS</sub> = 40 V; V <sub>GS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	0.02	1	μA
I <sub>GSS</sub>	gate leakage current	V <sub>GS</sub> = -10 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	2	100	nA
		V <sub>GS</sub> = 10 V; V <sub>DS</sub> = 0 V; T <sub>j</sub> = 25 °C	-	2	100	nA
R <sub>DSon</sub>	drain-source on-state resistance	V <sub>GS</sub> = 5 V; I <sub>D</sub> = 10 A; T <sub>j</sub> = 25 °C; <u>Fig. 11</u>	-	6	7.2	mΩ
		$V_{GS} = 5 \text{ V}; I_D = 10 \text{ A}; T_j = 175 °C;$ Fig. 11	-	12.1	14.5	mΩ
		V <sub>GS</sub> = 10 V; I <sub>D</sub> = 10 A; T <sub>j</sub> = 25 °C; Fig. 11; Fig. 12	-	5	6.1	mΩ
Dynamic ch	aracteristics FET1 and FE	T2				
Q <sub>G(tot)</sub>	total gate charge	I <sub>D</sub> = 10 A; V <sub>DS</sub> = 32 V; V <sub>GS</sub> = 5 V;	-	22.2	-	nC
Q <sub>GS</sub>	gate-source charge	T <sub>j</sub> = 25 °C; <u>Fig. 13</u> ; <u>Fig. 14</u>	-	5.2	-	nC
Q <sub>GD</sub>	gate-drain charge	1	-	6.8	-	nC
C <sub>iss</sub>	input capacitance	V <sub>DS</sub> = 25 V; V <sub>GS</sub> = 0 V; f = 1 MHz;	-	2250	3000	pF
C <sub>oss</sub>	output capacitance T <sub>j</sub> = 25 °C; <u>Fig. 15</u>	T <sub>j</sub> = 25 °C; <u>Fig. 15</u>	-	305	366	pF
C <sub>rss</sub>	reverse transfer capacitance		-	148	202	pF
t <sub>d(on)</sub>	turn-on delay time	$V_{DS} = 32 \text{ V}; R_L = 3.2 \Omega; V_{GS} = 5 \text{ V};$	-	13	-	ns
t <sub>r</sub>	rise time	$R_{G(ext)} = 5 \Omega; T_j = 25 °C$	-	22	-	ns

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Symbol	Parameter	Conditions	Min	Тур	Max	Unit
t <sub>d(off)</sub>	turn-off delay time		-	27	-	ns
t <sub>f</sub>	fall time		-	20	-	ns
Source-dra	in diode FET1 and FET2					
$V_{SD}$	source-drain voltage	$I_S = 25 \text{ A}$ ; $V_{GS} = 0 \text{ V}$ ; $T_j = 25 \text{ °C}$ ; Fig. 16	-	0.78	1.2	V
t <sub>rr</sub>	reverse recovery time	$I_S = 10 \text{ A}; dI_S/dt = -100 \text{ A/}\mu\text{s}; V_{GS} = 0 \text{ V};$	-	23	-	ns
Q <sub>r</sub>	recovered charge	V <sub>DS</sub> = 20 V; T <sub>j</sub> = 25 °C	-	18	-	nC

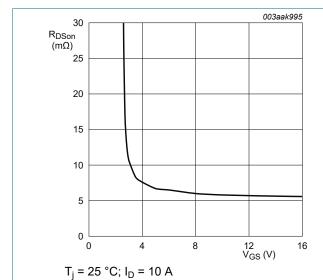


Fig. 6. Drain-source on-state resistance as a function of gate-source voltage; typical values

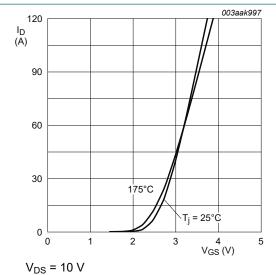


Fig. 8. Transfer characteristics; drain current as a function of gate-source voltage; typical values

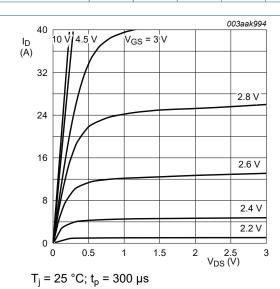
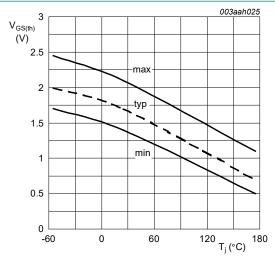


Fig. 7. Output characteristics; drain current as a function of drain-source voltage; typical values



 $I_D = 1 \text{ mA}; V_{DS} = V_{GS}$ 

Fig. 9. Gate-source threshold voltage as a function of junction temperature

### N-channel 40 V, 7.2 mOhm, logic level MOSFET in LFPAK56D using TrenchMOS technology

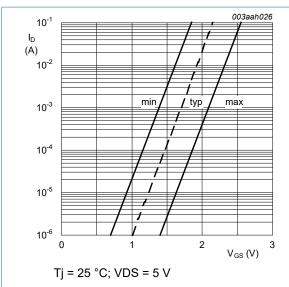


Fig. 10. Sub-threshold drain current as a function of gate-source voltage

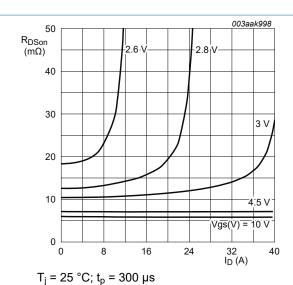


Fig. 11. Drain-source on-state resistance as a function of drain current; typical values

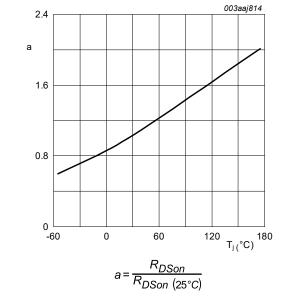


Fig. 12. Normalized drain-source on-state resistance factor as a function of junction temperature

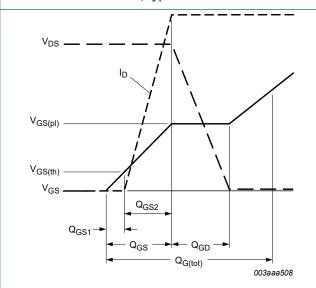


Fig. 13. Gate charge waveform definitions

### N-channel 40 V, 7.2 mOhm, logic level MOSFET in LFPAK56D using TrenchMOS technology

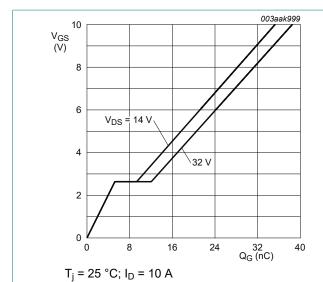
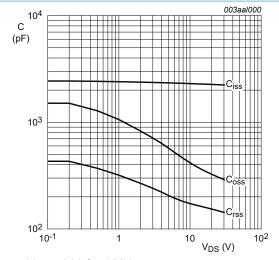
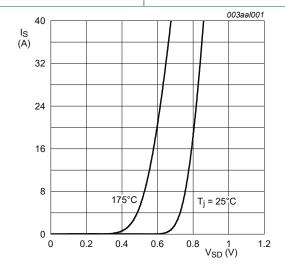


Fig. 14. Gate-source voltage as a function of gate charge; typical values



 $V_{GS} = 0 V$ ; f = 1 MHz

Fig. 15. Input, output and reverse transfer capacitances as a function of drain-source voltage; typical values



 $V_{GS} = 0 V$ 

Fig. 16. Source (diode forward) current as a function of source-drain (diode forward) voltage; typical values

N-channel 40 V, 7.2 mOhm, logic level MOSFET in LFPAK56D using TrenchMOS technology

# 11. Package outline

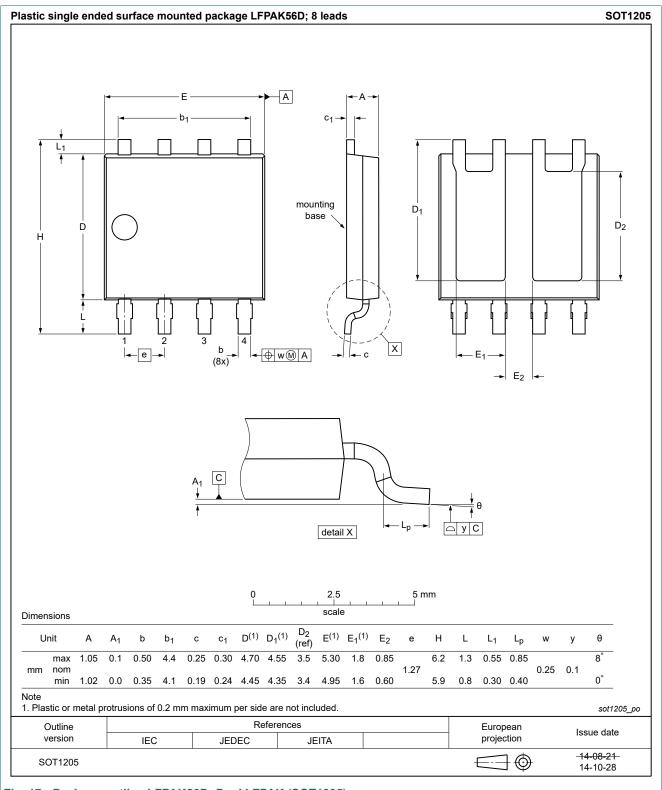
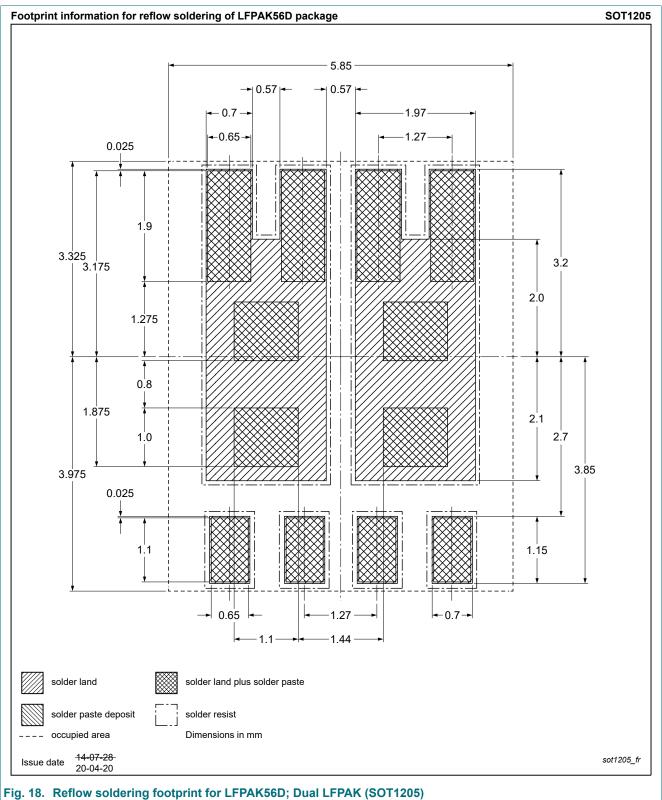


Fig. 17. Package outline LFPAK56D; Dual LFPAK (SOT1205)

N-channel 40 V, 7.2 mOhm, logic level MOSFET in LFPAK56D using TrenchMOS technology

# 12. Soldering



Tig. 10: Renow Soldering Toolprint for Elit Artoob, Dual Elit Art (0011200

#### N-channel 40 V, 7.2 mOhm, logic level MOSFET in LFPAK56D using TrenchMOS technology

## 13. Legal information

#### **Data sheet status**

Document status [1][2]	Product status [3]	Definition
Objective [short] data sheet	Development	This document contains data from the objective specification for product development.
Preliminary [short] data sheet	Qualification	This document contains data from the preliminary specification.
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